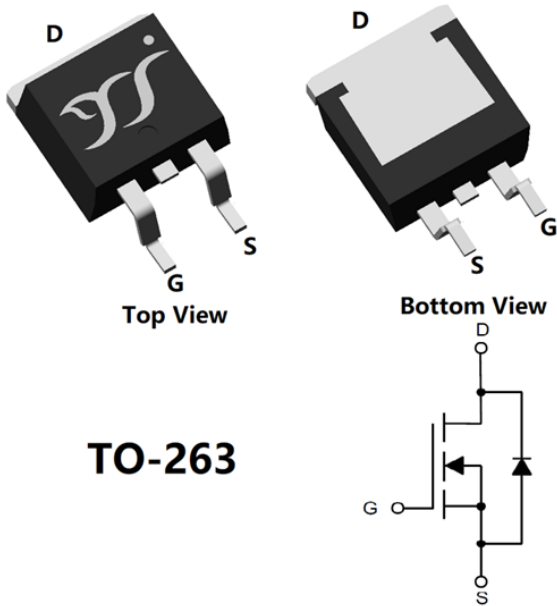




N-Channel Enhancement Mode Field Effect Transistor



TO-263

Product Summary

- V_{DS} 200V
- I_D 99A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<10.7m\Omega$
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- UPS and Inverter applications
- Motor drivers
- DC-DC convertor

Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit
Drain-source Voltage			V _{DS}	-	200	V
Gate-source Voltage			V _{GS}	-20	20	
Continuous Drain Current (Note 1,2)	Steady-State	T _A =25°C,V _{GS} = 10V	I _D	-	11.5	A
		T _A =100°C,V _{GS} = 10V		-	8.1	
Continuous Drain Current (Note 1,3)	Steady-State	T _C =25°C,V _{GS} = 10V,Chip limitation		-	99	
		T _C =100°C,V _{GS} = 10V		-	70	
Pulsed Drain Current	T _C =25°C ,t _p ≤ 10μs		I _{DM}	-	396	
Maximum Body-Diode Continuous Current	T _C =25°C		I _S		99	
Avalanche energy (non-repetitive)	T _J =25°C,V _G =10V,R _G =25Ω,L=0.5mH,I _{AS} =50A		EAS	-	625	mJ
Total Power Dissipation (Note 1,2)	Steady-State	T _A =25°C	P _D	-	3.7	W
		T _A =100°C		-	1.8	
Total Power Dissipation (Note 1,3)	Steady-State	T _C =25°C		-	277	
		T _C =100°C		-	138	
Junction and Storage Temperature Range			T _J , T _{STG}	-55	175	°C

Thermal Resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	Steady-State	$R_{\theta JA}$	-	40	$^{\circ}C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	0.54	

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJB011G20H	F2	YJB011G20H	800	/	8000	13" reel



YJB011G20H

■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA, T _J =25℃	200	-	-	V
		V _{GS} =0V, I _D =10mA, T _J =25℃	200	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =200V, V _{GS} =0V, T _J =25℃	-	-	1	μA
		V _{DS} =200V, V _{GS} =0V, T _J =125℃	-	-	100	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V, T _J =25℃	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA, T _J =25℃	2.2	3	3.8	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =50A, T _J =25℃	-	9.3	10.7	mΩ
Diode Forward Voltage	V _{SD}	I _S =50A, V _{GS} =0V, T _J =25℃	-	0.85	1.2	V
Gate Resistance	R _G	f=1MHz, T _J =25℃	-	0.8	-	Ω
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =100V, V _{GS} =0V, f=1MHz, T _J =25℃	-	3920	-	pF
Output Capacitance	C _{oss}		-	445	-	
Reverse Transfer Capacitance	C _{rss}		-	11.3	-	
Switching Parameters						
Total Gate Charge	Q _{ti}	V _{GS} =10V, V _{DS} =100V, I _D =50A, T _J =25℃	-	50.5	-	nC
Gate-Source Charge	Q _{gs}		-	18.4	-	
Gate-Drain Charge	Q _{gd}		-	8.2	-	
Reverse Recovery Charge	Q _{rr}	I _F =50A, di/dt=100A/μs, V _{GS} =0V, V _R =100V, T _J =25℃	-	513	-	nC
Reverse Recovery Time	t _{rr}		-	135	-	ns
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DS} =100V, I _D =50A, R _{GEN} =3Ω, T _J =25℃	-	20	-	ns
Turn-on Rise Time	t _r		-	42	-	
Turn-off Delay Time	t _{D(off)}		-	32	-	
Turn-off Fall Time	t _f		-	9	-	

Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^{\circ}C$. The maximum allowed junction temperature of $175^{\circ}C$. The value in any given application depends on the user's specific board design.
- Thermal resistance from junction to soldering point (on the exposed drain pad).



■ Typical Electrical and Thermal Characteristics Diagrams

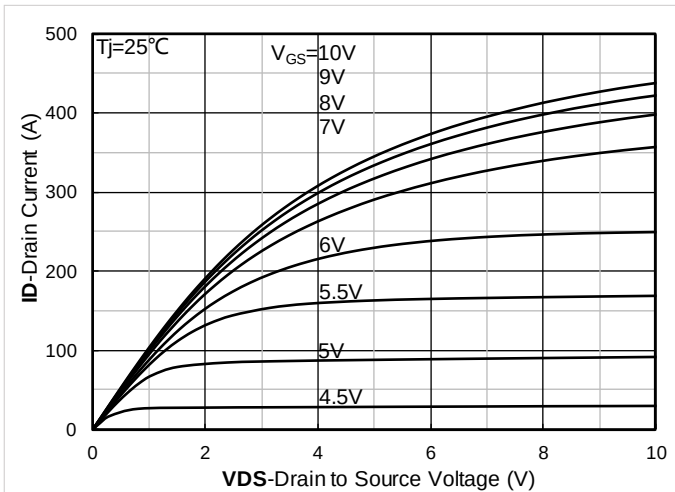


Figure 1. Output Characteristics; typical values

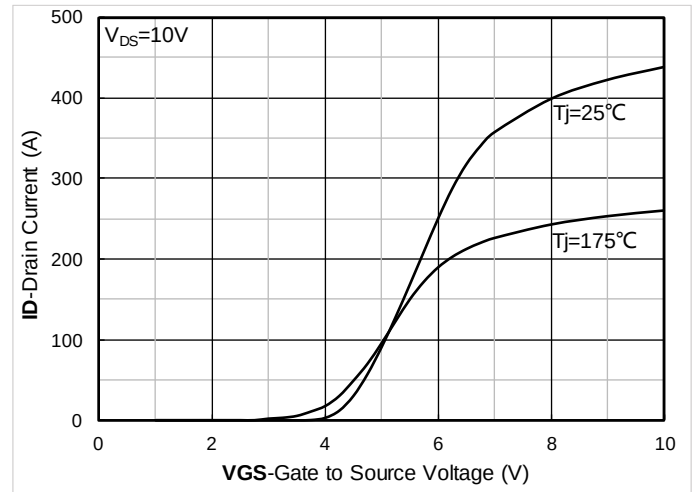


Figure 2. Transfer Characteristics; typical values

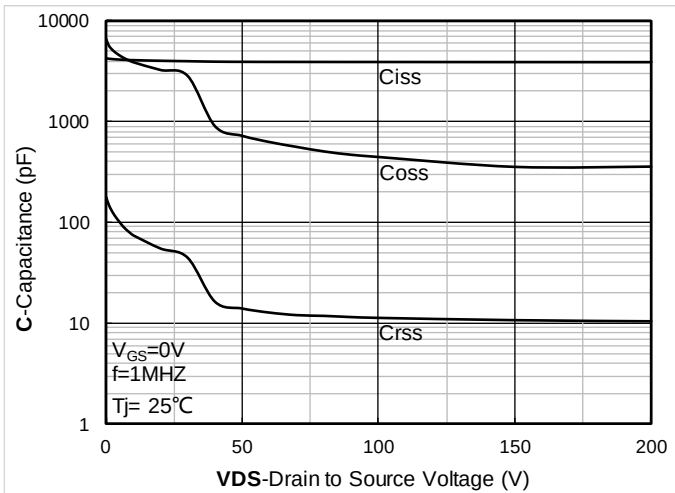


Figure 3. Capacitance Characteristics; typical values

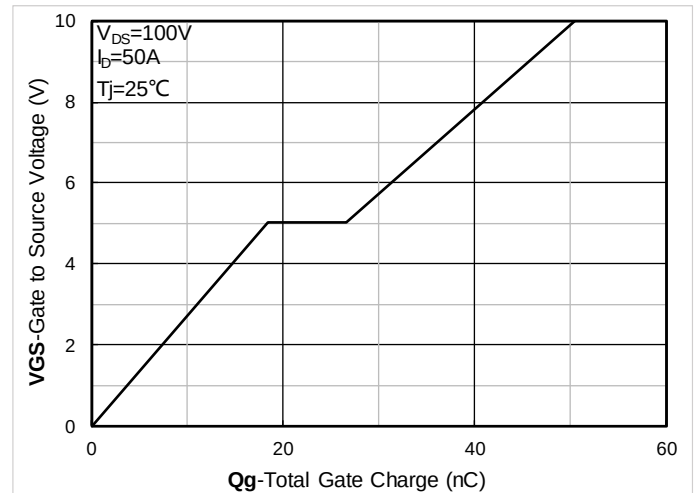


Figure 4. Gate Charge; typical values

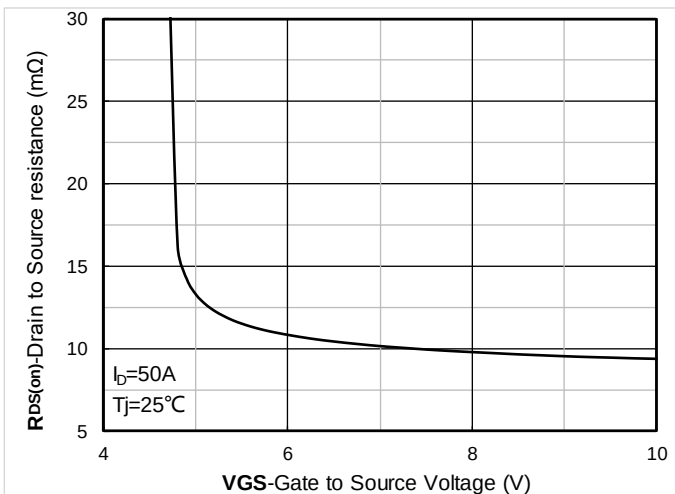


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

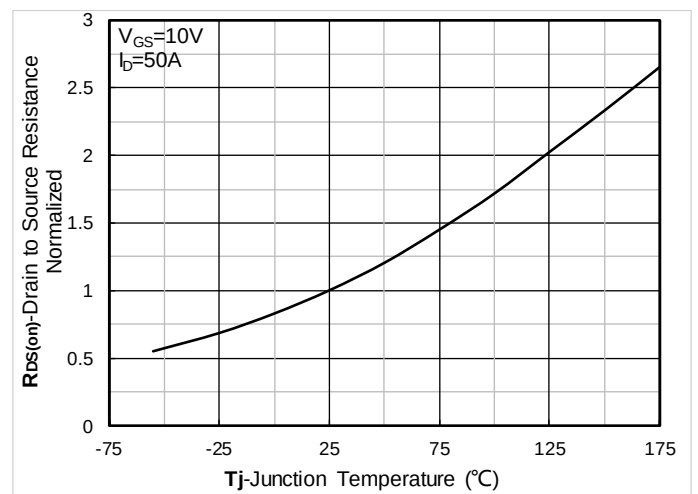


Figure 6. Normalized On-Resistance

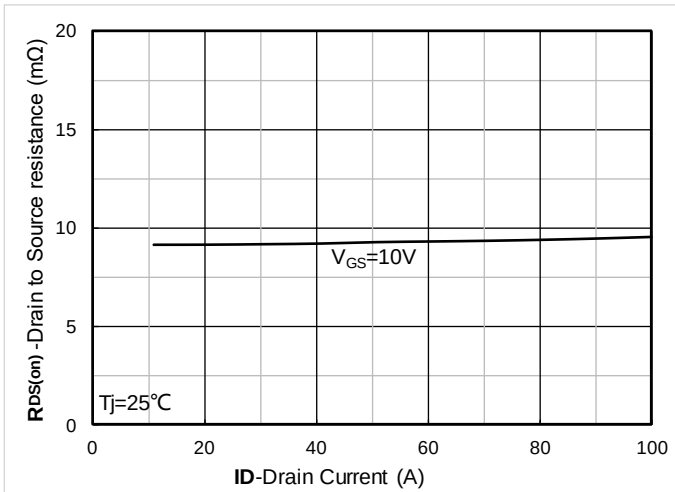


Figure 7. $R_{DS(on)}$ vs. Drain Current; typical values

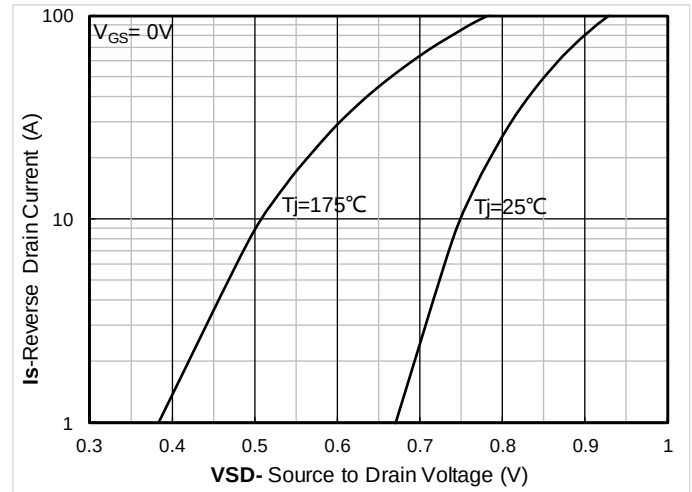


Figure 8. Forward characteristics of reverse diode; typical values

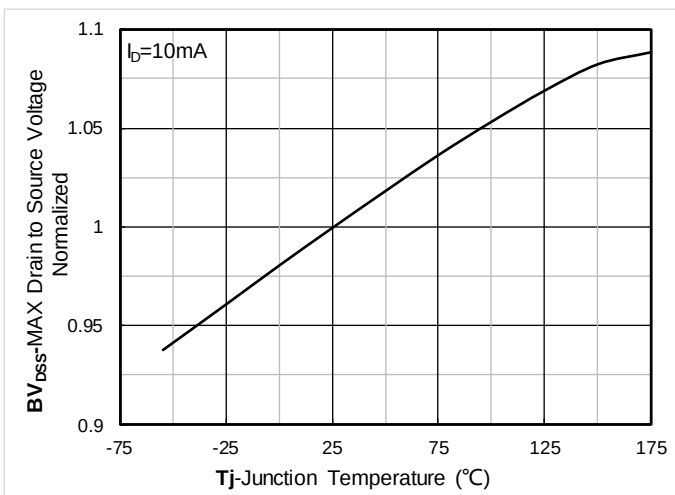


Figure 9. Normalized breakdown voltage

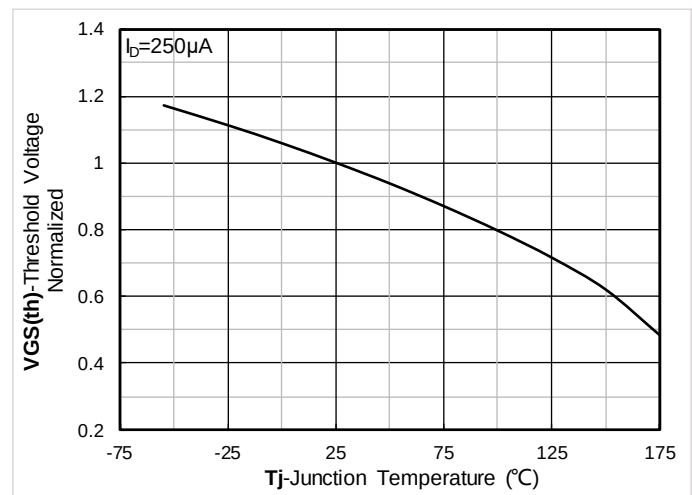


Figure 10. Normalized Threshold voltage

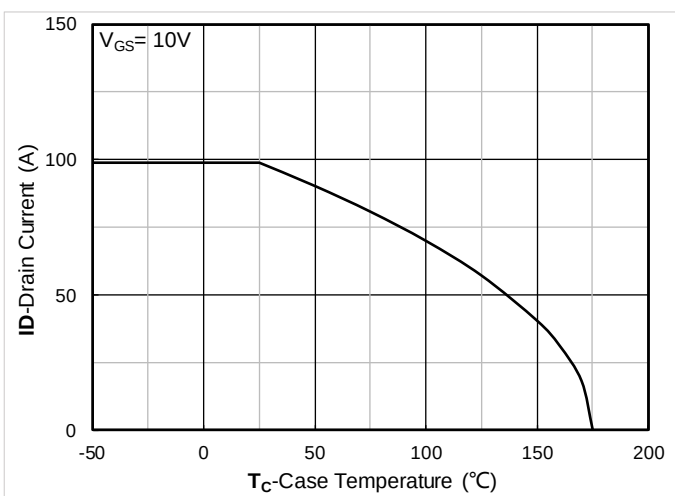


Figure 11. Current dissipation

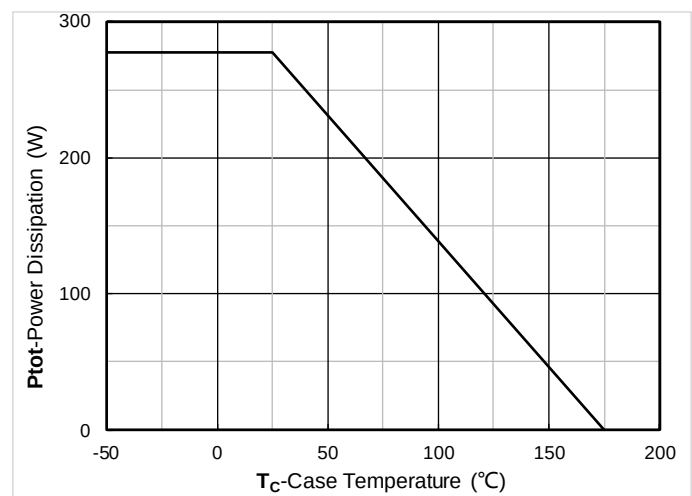


Figure 12. Power dissipation

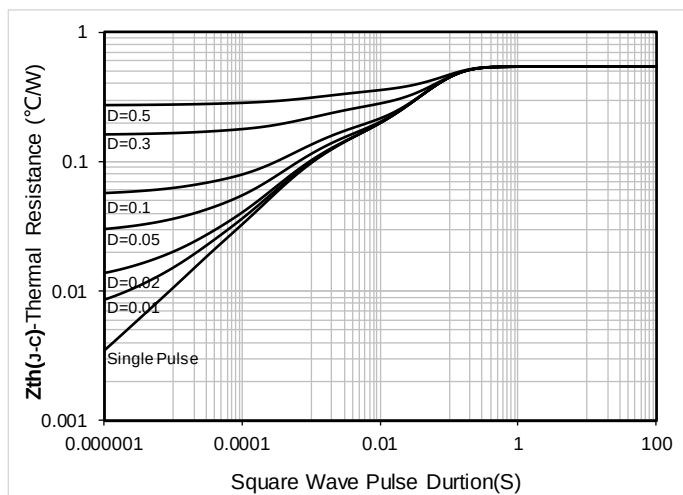


Figure 13. Maximum Transient Thermal Impedance

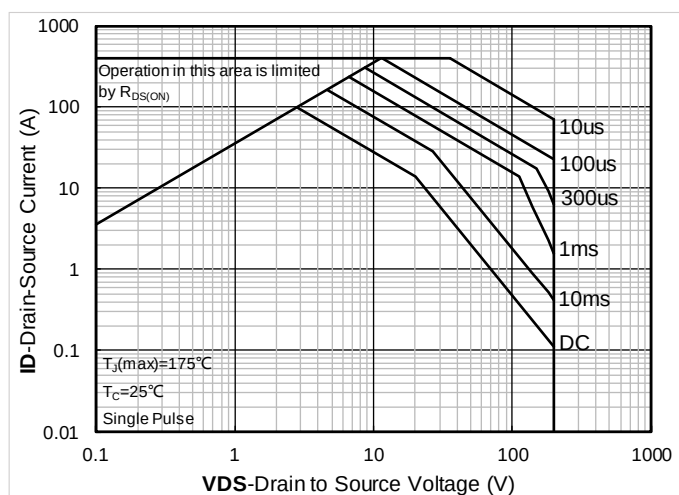


Figure 14. Safe Operation Area

■ Test Circuits & Waveforms

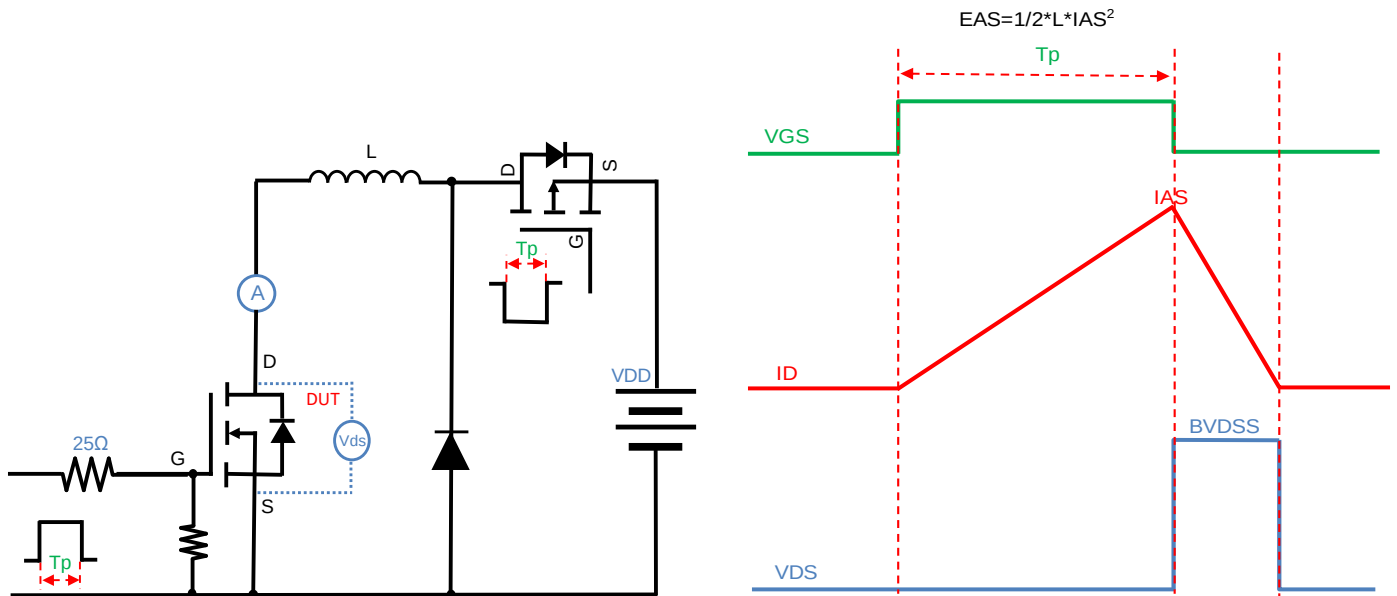


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

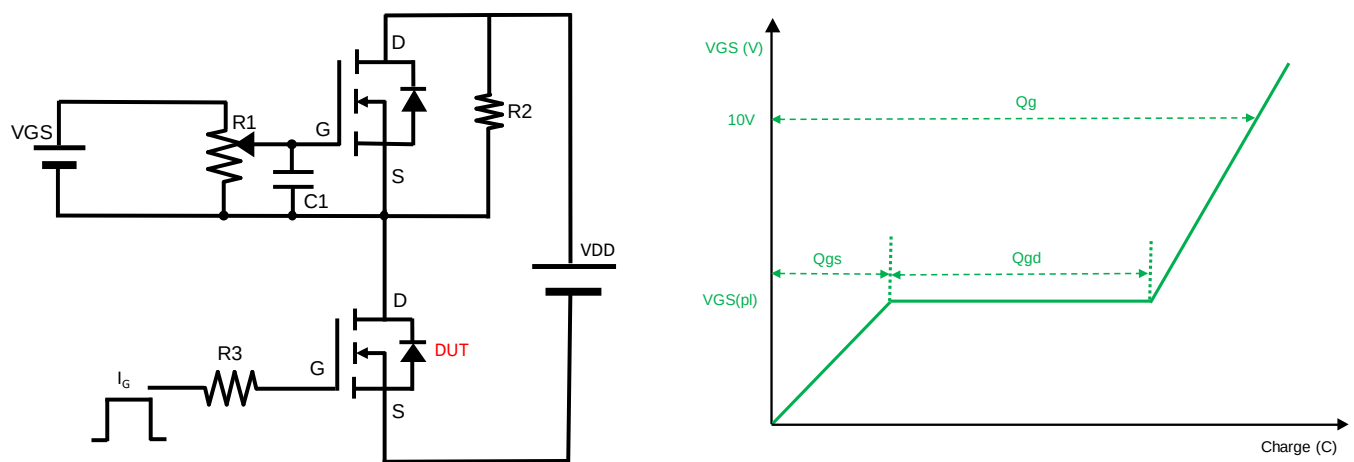


Figure B. Gate Charge Test Circuit & Waveform

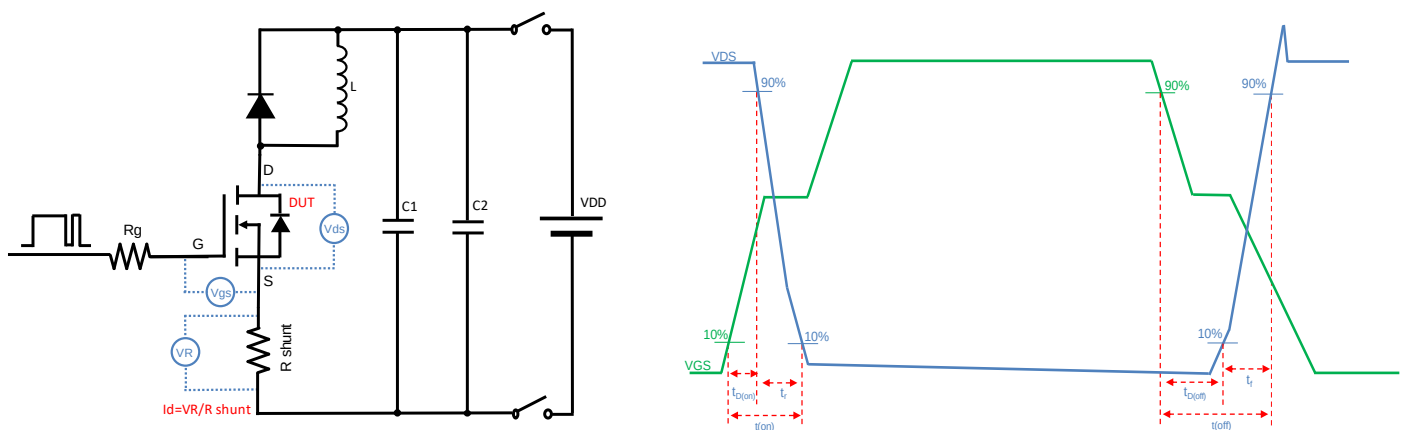


Figure C. Resistive Switching Test Circuit & Waveform

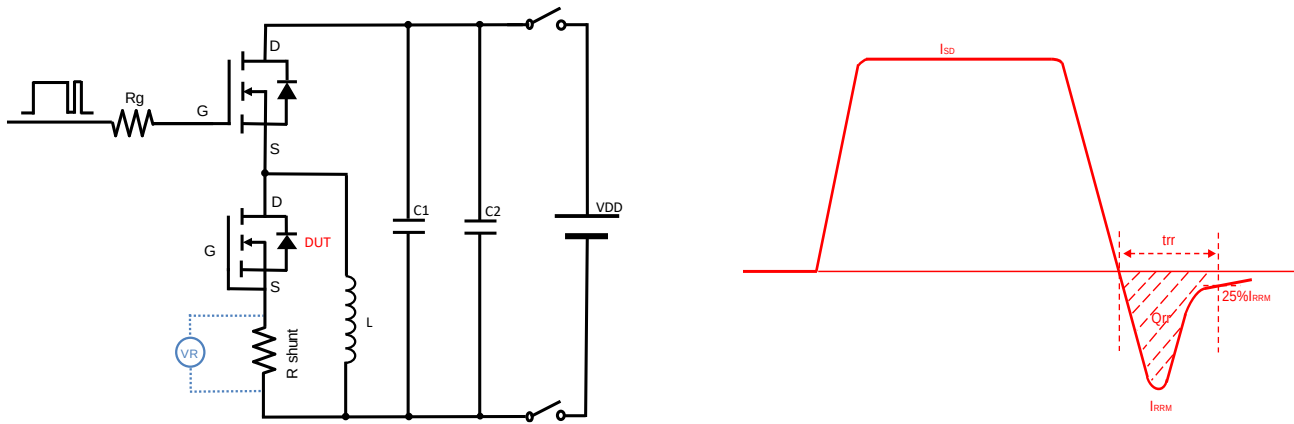
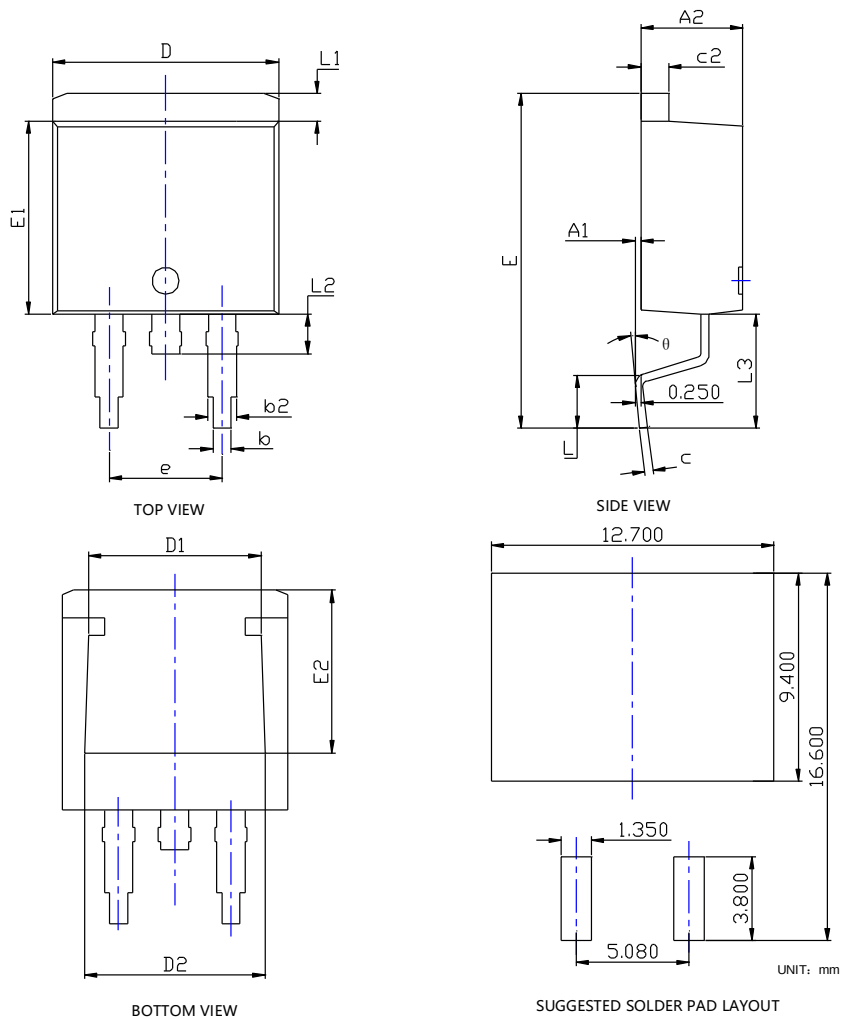


Figure D. Diode Recovery Test Circuit & Waveform



YJB011G20H

■ TO-263-HY Package information



SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
A1	0.000	---	0.010	0.000	---	0.250
A2	0.174	0.180	0.186	4.430	4.580	4.730
b	0.028	0.032	0.036	0.720	0.820	0.920
b2	0.046	0.050	0.054	1.180	1.280	1.380
c	0.013	0.015	0.018	0.330	0.390	0.450
c2	0.048	0.050	0.053	1.220	1.280	1.340
D	0.394	0.400	0.406	10.000	10.150	10.300
D1	0.295	0.307	0.319	7.500	7.800	8.100
D2	0.303	0.315	0.327	7.700	8.000	8.300
E	0.571	0.591	0.610	14.500	15.000	15.500
E1	0.337	0.341	0.348	8.550	8.700	8.850
E2	0.276	0.287	0.299	7.000	7.300	7.600
e	0.200BSC			5.080BSC		
L	0.070	---	0.110	1.790	---	2.790
L1	0.044	---	0.056	1.120	---	1.420
L2	0.030	---	0.070	0.770	---	1.770
L3	0.197REF			5.000REF		
θ	0°	---	8°	0°	---	8°

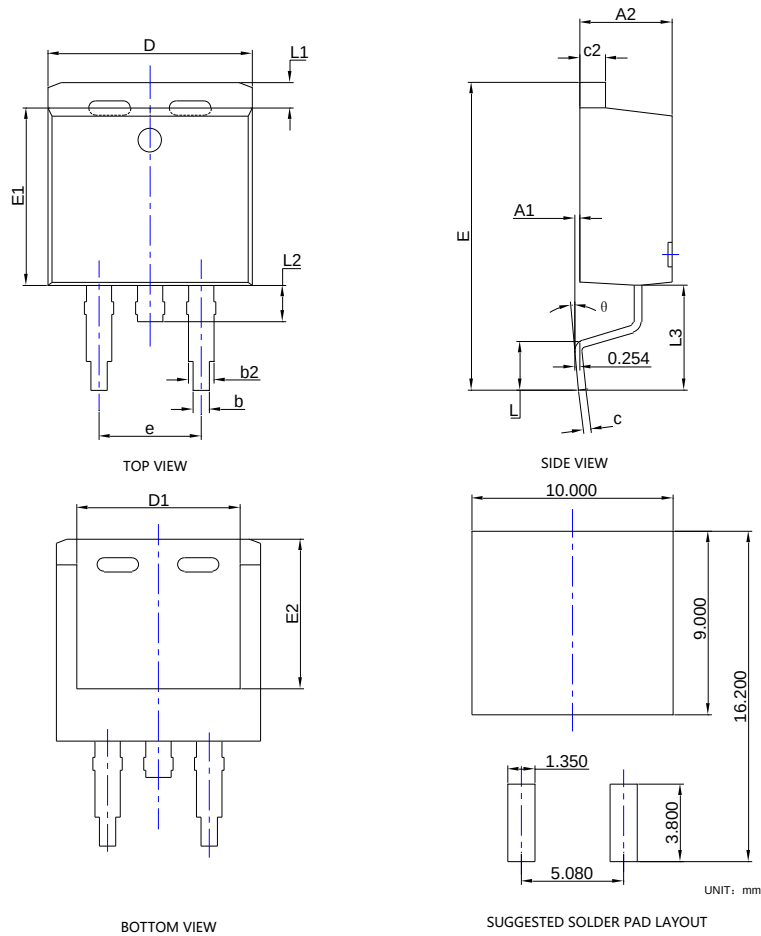
NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



YJB011G20H

■ TO-263-B Package information



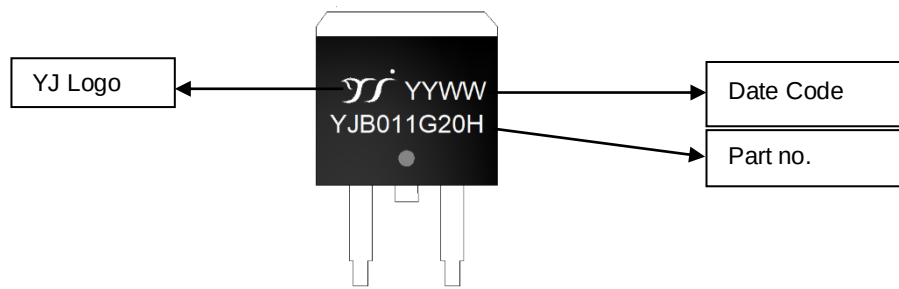
SYMBOL	DIMENSIONS			
	INCHES		MILLIMETER	
	MIN.	MAX.	MIN.	MAX.
A1	0.000	0.010	0.000	0.254
A2	0.160	0.190	4.064	4.826
b	0.020	0.039	0.508	0.991
b2	0.045	0.070	1.143	1.778
c	0.015	0.029	0.381	0.737
c2	0.045	0.065	1.143	1.651
D	0.380	0.420	9.652	10.668
D1	0.245	---	6.223	---
E	0.575	0.625	14.605	15.875
E1	0.330	0.380	8.382	9.652
E2	0.270	---	6.858	---
e	0.200BSC		5.08BSC	
L	0.070	0.110	1.778	2.794
L1	---	0.066	---	1.676
L2	---	0.070	---	1.778
L3	0.188	0.208	4.780	5.280
θ	0°	8°	0°	8°

NOTE:
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



YJB011G20H

■ Marking Information



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. YJB011G20H is part no., YYWW is date code, “YY” is year, “WW” is week
4. Body color: Black



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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

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